

Amendments to the Specification

Please add the following paragraph between the title and the first line of text as follows:

This is a Division of Application No. 10/011,291 filed December 11, 2001, which claims the benefit of Japanese Patent Application No. 2000-384382 filed December 18, 2000. The entire disclosure of the prior application is hereby incorporated by reference herein in its entirety.

Please replace the paragraph beginning on page 43, line 6, with the following rewritten paragraph:

FIG. 22 is a characteristic diagram illustrating another example of the results of measurements conducted to determine the relationship between the processing conditions for the adhering step and change in the characteristics of the electronic component 13 between before and after the adhering step. FIG. 22 shows changes in the transmission characteristics of the band pass filter between before and after the adhering step. In FIG. 22, the horizontal axis represents frequency and the vertical axis represents S_{21} parameter. FIG. 22 shows in detail the transmission characteristics in the frequency range where the S_{21} parameter has values from 0.0 to -5.0 dB. In this example, the adhering step was carried out under four different conditions, that is, by varying the number of times of the heat treatment, to measure the transmission characteristics of the band pass filter after the adhering step each time. At each heat treatment, the resin film 15 was heated at 180°C for one hour. In this example, the resin film 15 is formed of an epoxy-based resin, and the content of a hardening accelerator in the epoxy-based resin is 0.1 wt%. In FIG. 22, the solid line indicates the transmission characteristics obtained before the electronic component 13 is sealed, that is, before the adhering step. On the other hand, the alternate long and short dashed lines indicate the

transmission characteristics obtained after the adhering step in which the heat treatment was performed once. The chain double-dashed line indicates the transmission characteristics obtained after the adhering step in which the heat treatment was performed twice. The dashed line indicates the transmission characteristics obtained after the adhering step in which the heat treatment was performed three times. The dotted line indicates the transmission characteristics after the adhering step in which the heat treatment was performed four times. In the example shown in FIG. 22, the larger the number of times of the heat treatment in the adhering step, the greater the amount of change in the center frequency in the pass band of the band pass filter between before and after the adhering step.

Please replace the paragraph beginning on page 49, line 19, with the following rewritten paragraph:

According to a second method, in manufacturing the electronic device 10, the electronic component 13 is fabricated in expectation of a change in the characteristics of the electronic component 13 between before and after the adhering step, so as to attain desired characteristics of the electronic component 13 after the adhering step. For example, this method is accomplished as follows. First, the processing conditions to be employed in the adhering step are determined such that the amount of change in the center frequency between before and after the adhering step will fall within a predetermined amount. Then, in expectation of the change in the center frequency between before and after the adhering step, the electronic component 13 is fabricated so as to obtain a desired center frequency after the adhering step. This means that the electronic component 13 is fabricated such that the center frequency shifts from the desired frequency by the predetermined amount. The adhering step is then carried out under the predetermined conditions, thereby attaining a center frequency to the desired frequency.